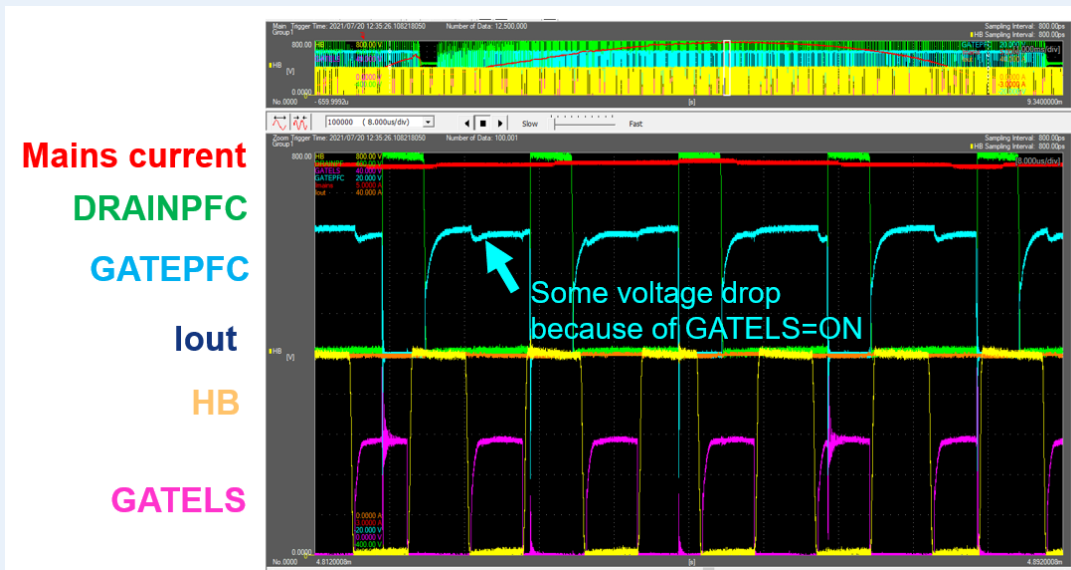


Improvements TEA2016AAT/2 vs. the TEA2016AAT/1

TEA2016AAT/1

EZHV SOI process used for the High Voltage die

Reference Driver



TEA2016AAT/2

New improved ABCD3HV SOI process used for the High Voltage die:

- Better noise immunity for high dv/dt
- The /2 operation is much more robust to high Half Bridge dV/dt events

Driver TEA2016AAT/2: improved driver performance

